PROCEEDINGS OF SPIE

# *Sensor Systems and Networks: Phenomena, Technology, and Applications for NDE and Health Monitoring 2007*

**Kara J. Peters**
*Editor*

**19–21 March 2007**
**San Diego, California, USA**

*Sponsored and Published by*
SPIE—The International Society for Optical Engineering

*Cosponsored by*
American Society of Mechanical Engineers (USA)

*Cooperating Organizations*
Intelligent Materials Forum (Japan)
Jet Propulsion Laboratory (USA)
National Science Foundation (USA)

Volume 6530

The International Society for Optical Engineering

Proceedings of SPIE—The International Society for Optical Engineering, 9780819466518, v. 6530

The papers included in this volume were part of the technical conference cited on the cover and title page. Papers were selected and subject to review by the editors and conference program committee. Some conference presentations may not be available for publication. The papers published in these proceedings reflect the work and thoughts of the authors and are published herein as submitted. The publisher is not responsible for the validity of the information or for any outcomes resulting from reliance thereon.

Please use the following format to cite material from this book:
Author(s), "Title of Paper," in *Sensor Systems and Networks: Phenomena, Technology, and Applications for NDE and Health Monitoring 2007*, edited by Kara J. Peters, Proceedings of SPIE Vol. 6530 (SPIE, Bellingham, WA, 2007) Article CID Number.

ISSN 0277-786X
ISBN 9780819466518

Published by
**SPIE—The International Society for Optical Engineering**
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone 1 360/676-3290 (Pacific Time) · Fax 1 360/647-1445
http://www.spie.org



Printed in the United States of America.

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**Pagination:** Proceedings of SPIE follow an e-First publication model, with papers published first online and then in print and on CD-ROM. Papers are published as they are submitted and meet publication criteria. A unique, consistent, permanent citation identifier (CID) number is assigned to each article at the time of the first publication. Utilization of CIDs allows articles to be fully citable as soon they are published online, and connects the same identifier to all online, print, and electronic versions of the publication. SPIE uses a six-digit CID article numbering system in which:

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